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(54) **SEMICONDUCTOR PACKAGE AND METHOD OF MANUFACTURING THE SAME**

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(57) **ABSTRACT**

A semiconductor package includes a first substrate, a pattern layer disposed on the first substrate, a first chip member disposed on a surface of the first substrate, lead frames mounted on the first substrate surrounding the first chip member, and a first encapsulation layer disposed on the first substrate, encapsulating the first chip member and the lead frame, wherein upper end portions of the lead frame and the first encapsulation layer are removed, and lead frame columns are exposed through the first encapsulation layer.

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